

ABSTRACT

A semiconductor device comprising a signal transmission line of a microstrip structure, capable of increasing the characteristic impedance of the signal transmission line and reducing coupling between a plurality of signal lines. In a signal transmission line of a microstrip structure composed of a signal line and a ground plate, the capacitance between wires is reduced and the characteristic impedance can be increased by forming holes in the signal line or in the ground plate. The coupling between a plurality of signal lines can also be reduced.